



**TARGET THICKNESS: 0.125"**  
**NUMBER OF LAYERS: 12**

# MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

<b>12 Layer StackUp (0.125") L12-125-1ozHoz</b>		<b>Thickness (inches)</b>
<b>Layer 1</b>	<b>.5 oz foil plated to approximate* thickness 0.0017"</b>	0.0017
Prepreg	Bonding ply (3x2116) Average Dielectric Constant 4.5	0.0126
<b>Layer 2</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.01
<b>Layer 3</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
<b>Layer 4</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.01
<b>Layer 5</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
<b>Layer 6</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.01
<b>Layer 7</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
<b>Layer 8</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.01
<b>Layer 9</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
<b>Layer 10</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.01
<b>Layer 11</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (3x2116) Average Dielectric Constant 4.5	0.0126
<b>Layer 12</b>	<b>.5 oz foil plated to approximate* thickness 0.0017"</b>	0.0017
<b>"Thickness does not include soldermask or surface finish"</b>		<b>0.1245</b>

## NOTES: